

LMT043DFFFWD-NAA

LCD Module User Manual

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Rev.	Descriptions	Release Date
0.1	Preliminary new release	2016-11-23

URL: www.topwaydisplay.com www.topwaysz.com

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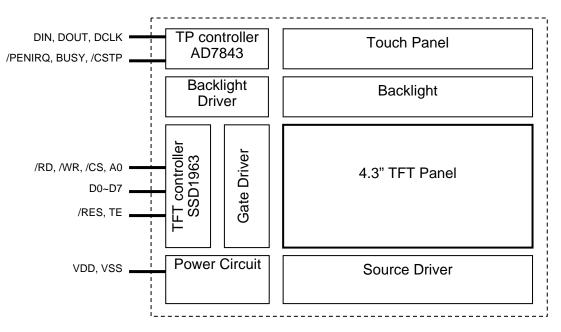
1. General Specification

Screen Size(Diagonal) : Resolution : Signal Interface : Color Depth : Dot Pitch : Pixel Configuration : Display Mode : Surface Treatment : Viewing Direction :	 4.3 inch 480(RGB) x 272 8bit data, 1bit address, 8080mode 16.7M color (24bit) (*1) 0.198 x 0.198 (mm) RGB Stripe Transmissive / Positive (normal white) Anti-Glare Treatment 12 o'clock (Gray Scale Inversion Direction) (*2)
Outline Dimension : Active Area : Backlight : Operating Temperature :	6 o'clock (*3) 121.0 x 70.0 x 10.7 (MAX) (mm) (see attached drawing for details) 95.0x 53.86 (mm) White LED -20 ~ +70°C
Storage Temperature : Note:	-20 ~ +70 C -30 ~ +80°C

*1 Color tune may slightly changed by temperature and driving voltage.

*2 For saturated color display content (eg. pure-red, pure-green, pure-blue or pure-colors-combinations). *3 For "color scales" display content.

2. Block Diagram



3. K1 Terminal Function (Input Terminal)

1 VSS P Power Supply GND (0V) 3 VDD I Positive Power Supply (3.3 V) 4 VDD I Positive Power Supply (3.3 V) 5 A0 I A0=0, command A0=1, data or parameter 6 /CS I Chip Select signal 7 /RES I /RES=1, normal /RES=0, reset execute 8 D0 . 1: I/O 8bit Data bus 15 D7	No.	Pin Name	I/O	Descriptions
2 Image: Construction of the sector of t		221	P	Power Supply GND (0)/)
4 VDD 1 Positive Power Supply (3.3 V) 4 VDD 1 Register Select 5 A0 1 A0=0, command A0=1, data or parameter 6 /CS 1 Chip Select signal 7 /RES 1 Chip Select signal 7 /RES 1 /RES=1, normal /RES=0, reset execute 8 D0 8bit Data bus 15 D7 1 16 TE O 17 /RD 1 18 /WR 1 19 NC - 20 NC - 21 /PENIRQ O Pen Interrupt (*2)(*3) 22 DOUT O Data Output(*3) 23 BUSY O Busy Output(*3) 24 DIN 1 Data Input(*3) 25 /CSTP 1 Chip Select, also for initiating the conversions(*3)		100		
4 A0 I Register Select 5 A0 I A0=0, command A0=1, data or parameter 6 /CS I Chip Select signal 7 /RES I Chip Select signal 7 /RES I /RES=1, normal /RES=0, reset execute 8 D0	3	חחע	1	Positive Power Supply (3.3.\/)
5 A0 I A0=0, command A0=1, data or parameter 6 /CS I Chip Select signal 7 /RES I Reset signal, /RES=0, reset execute 8 D0 /RES=0, reset execute 8 D0 /RES=0, reset execute 16 TE O 7 /RD I 16 TE O 18 /WR I 19 NC - 20 NC - 21 /PENIRQ O 22 DOUT O 23 BUSY O 24 DIN I 25 /CSTP I	4	VUU		
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8D0/RES=0, reset execute8D0I/O1I/O15D716TEO17/RDI18/WRI19NC20NC21/PENIRQO22DOUTO23BUSYO24DINI25/CSTPIChip Select, also for initiating the conversions(*3)				
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17/RDIRead signal18/WRIWrite signal19NC-No Connection20NC-No Connection21/PENIRQOPen Interrupt (*2)(*3)22DOUTOData Output(*3)23BUSYOBusy Output(*3)24DINIData Input(*3)25/CSTPIChip Select, also for initiating the conversions(*3)	15	D7		
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20 NC - No Connection 21 /PENIRQ O Pen Interrupt (*2)(*3) 22 DOUT O Data Output(*3) 23 BUSY O Busy Output(*3) 24 DIN I Data Input(*3) 25 /CSTP I Chip Select, also for initiating the conversions(*3)	18	/WR		Write signal
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22 DOUT O Data Output(*3) 23 BUSY O Busy Output(*3) 24 DIN I Data Input(*3) 25 /CSTP I Chip Select, also for initiating the conversions(*3)	20	NC] -	
23 BUSY O Busy Output(*3) 24 DIN I Data Input(*3) 25 /CSTP I Chip Select, also for initiating the conversions(*3)	21	/PENIRQ	0	Pen Interrupt (*2)(*3)
24 DIN I Data Input(*3) 25 /CSTP I Chip Select, also for initiating the conversions(*3)	22	DOUT	0	Data Output(*3)
25 /CSTP I Chip Select, also for initiating the conversions(*3)	23	BUSY	0	Busy Output(*3)
	24	DIN	Ι	Data Input(*3)
26 DCLK I Clock Input for Serial Data & conversions(*3)	25	/CSTP	Ι	Chip Select, also for initiating the conversions(*3)
	26	DCLK	Ι	Clock Input for Serial Data & conversions(*3)

Note.

*1. Tear signal may leave open when not use*2. Pulled-up by internal resistor

*3. It is Touch Panel Controller's communication interface

4. Absolute Maximum Ratings

Items	Symbol	Min.	Max.	Unit	Condition
Power Supply voltage	V _{DD}	-0.3	4.0	V	
Operating Temperature	T _{OP}	-20	70	°C	No Condensation
Storage Temperature	T _{ST}	-30	80	°C	No Condensation

Note:

*1. This rating applies to all parts of the module. And should not be exceeded.

*2. The operating temperature only guarantees operation of the circuit. The contrast, response speed,

and the other specification related to electro-optical display quality is determined at the room temperature, $T_{OP}=25^{\circ}C$ *3. Ambient temperature when the backlight is lit (reference value)

*4. Any Stresses exceeding the Absolute Maximum Ratings may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

5. Electrical Characteristics

5.1 DC Characteristics

				VDD =	3.3V,Top=25℃, VSS=0V
Symbol	Min.	Тур.	Max.	Unit	Remark
V_{DD}	3.1	3.3	3.6	V	*2
V _{IH}	0.85VDD	-	VDD	V	*2, *3
VIL	0	-	0.4	V	*2, *3
V _{OH}	0.7VDD	-	VDD	V	*2, *3
V _{OL}	0	-	0.8	V	*2, *3
I _{VDD}	-	260.0	-	mA	Backlight (100%PWM)
	V _{DD} V _{IH} V _{IL} V _{OH} V _{OL}	$\begin{array}{c c c} V_{DD} & 3.1 \\ \hline V_{IH} & 0.85 VDD \\ \hline V_{IL} & 0 \\ \hline V_{OH} & 0.7 VDD \\ \hline V_{OL} & 0 \\ \hline \end{array}$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

Note:

*1. Never Apply logic signal before the VDD supply.

*2. VDD setting should match the signals voltage

*3. For all the inputs signals

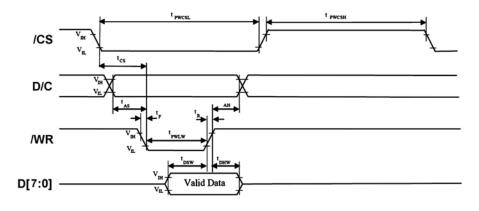
*4. PLL Clock Freq=200MHz

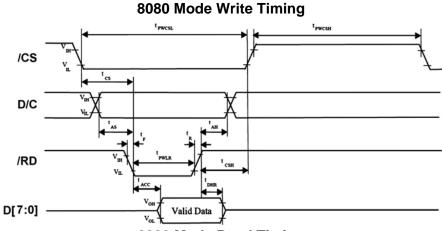
5.2 Touch panel Characteristics

Items	MIN.	TYP.	MAX.	Unit	Note
Surface hardness	3	-	-	Н	-
Operating Force	30	-	160	g	-
Life Time	-	1,000,000	-	times	-
linearity	-1.5	-	+1.5	%	-
Transparency	78	-	-	%	-
Operation temperature	-20	-	70	°C	-
Storage temperature	-30	-	80	°C	-

6. AC Characteristics

6.1 TFT Controller Timing Characteristics





8080 Mode Read Timing

				V _{DD} =3.3V, ⁻	I _{OP} =25°C
Item	Symbol	MIN.	TYP.	MAX.	Unit
System Clock Period(*1)	t _{MCLK}	1/f _{MCLK}	-	-	ns
Control Pulse High Width Write	t _{PWCSL}	16	1.5*t _{MCLK}	-	ns
Read		38	1.3*t _{MCLK}	-	ns
Control Pulse Low Width Write (next write cycle)	+	16	1.5*t _{MCLK}	-	ns
Write (next read cycle)	t _{PWCSH}	100	9*t _{MCLK}	-	ns
Read		100	9*t _{MCLK}	-	ns
Address Setup Time	t _{AS}	1.3	-	-	ns
Address Hold Time	t _{AH}	2.5	-	-	ns
Write Data Setup Time	t _{DSW}	5	-	-	ns
Write Data Hold Time	t _{DHW}	1.3	-	-	ns
Write Low Time	t _{PWLW}	15	-	-	ns
Read Data Hold Time	t _{DHR}	1.3	-	-	ns
Access Time	t _{ACC}	40	-	-	ns
Read Low Time	t _{PWLR}	45	-	-	ns
Rise Time	t _R	-	-	0.4	ns
Fall Time	t _F	-	-	0.4	ns
Chip select setup time	t _{CS}	2.5	-	-	ns
Chip select hold time to read signal	t _{CSH}	4	-	-	ns

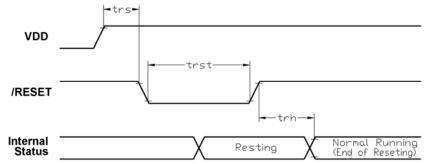
Note:

*1. t_{MCLK} is the System Clock Period, which may config by internal PLL setting

*2. LMT043DFFFWD-NNA is driving by external 10MHz, and clock up by enabling the SSD1963 internal PLL

*3. Suggested PLL clock setting is 200MHz

6.1.1 **TFT Controller Reset Timing**



 $V_{SS}=0V$, $V_{DD}=3.3V$, $T_{OP}=25^{\circ}C$

Item	Symbol	MIN.	TYP.	MAX.	Unit
Reset setup time	trs	2	-	-	ms
Reset pulse	trst	0.2	-	-	ms
Reset hold time	trh	2	-	-	ms

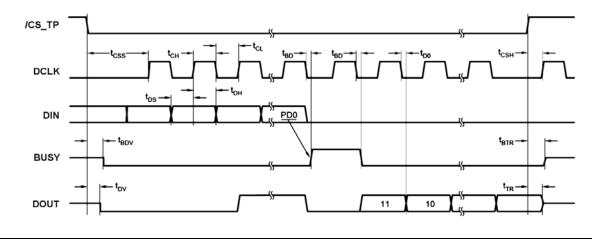
6.2 **Touch Panel Controller Timing Characteristics**

6.2.1 ADS7843 Digital Timing

			VSS=0V	, VDD=3.3	V, T _{OP} =25°C
Item	Symbol	MIN.	TYP.	MAX.	Unit
Acquisition Time	t _{ACQ}	1.9	-	-	us
DIN Valid Prior to DCLK Rising	t _{DS}	125	-	-	ns
DIN Hold After DCLK HIGH	t _{DH}	13	-	-	ns
DCLK Falling to DOUT Valid	t _{DO}	-	-	250	ns
/CS_TP Falling to DOUT Enabled	t _{DV}	-	-	160	ns
/CS_TP Rising to DOUT Disabled	t _{TR}	-	-	250	ns
/CS_TP Falling to First DCLK Rising	t _{CSS}	125	-	-	ns
/CS_TP Rising to DCLK Ignored	t _{CSH}	10	-	-	ns
DCLK HIGH	t _{CH}	250	-	-	ns
DCLK LOW	t _{CL}	250	-	-	ns
DCLK Falling to BUSY Rising	t _{BD}	-	-	250	ns
/CS_TP Falling to BUSY Enabled	t _{BDV}	-	-	160	ns
/CS_TP Rising to BUSY Disabled	t _{BTR}	-	-	250	ns

Note. Please Refer to ADS7843E datasheet for details.

6.2.2 **Timing diagram**



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7. Optical Characteristics

ltem		Symbol	Condition	Min	Тур	Мах	Unit	Remark	
		θΤ		60	70				
View Angles		θΒ	CR≧10	40	50		Degree	Noto 2	
VIEW Aligies		θL		60	70		Degree	NOICE 2	
		θR		60	70				
Contrast Ratio		CR	θ=0°	400	500			Note1、Note3	
Response Tim	е	T _{ON}	25 ℃		20	30	ms	Note1 Note4	
		T _{OFF}						NOIE4	
	White x	0.265	0.315	0.365					
		У		0.285	0.335	0.385			
	Red	х		0.531	0.581	0.631			
Chromaticity	i teu	у	Backlight	0.295	0.345	0.395		Note5	
Oniomationy	Green	Х	is on	0.298	0.348	0.395		Note1	
	Gleen	у		0.531	0.581	0.631			
	Blue	х		0.103	0.153	0.203			
Diue		у		0.045	0.095	0.145			
Uniformity		U		75	80		%	Note1、Note6	
NTSC					50		%	Note 5	
Luminance		L		250	300		cd/m ²	Note1、Note7	

Note:

The parameter is slightly changed by temperature, driving voltage and materiel Please see the Notes for testing conditions

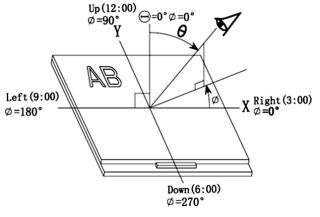
Note 1:

The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment SR-3A (1°) Measuring condition:

- Measuring surroundings: Dark room
- Measuring temperature: Ta=25°C.
- Adjust operating voltage to get optimum contrast at the center of the display.

Note 2:

The definition of viewing angle: Refer to the graph below marked by θ and ϕ



Note 3:

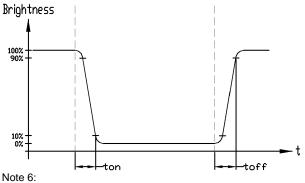
The definition of contrast ratio (Test LCM using SR-3A (1°)):

Luminance When LCD is at "White" state Contrast Luminance When LCD is at "Black" state Ratio(CR) (Contrast Ratio is measured in optimum common electrode voltage)

Note 4:

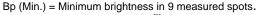
Definition of Response time. (Test LCD using BM-7A(2°)): The output signals of photo detector are measured when the input signals are changed from "black" to "white"(falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes.Refer to

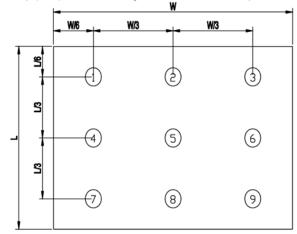
figure as below.



The luminance uniformity is calculated by using following formula. \triangle Bp = Bp (Min.) / Bp (Max.)×100 (%)

Bp (Max.) = Maximum brightness in 9 measured spots

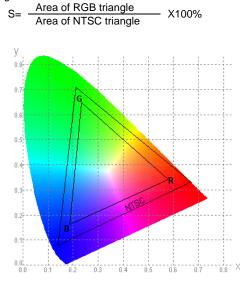




Note 7: Measured the luminance of white state at center point

Note 5: Definition of Color of CIE1931 Coordinate and NTSC Ratio.

Color gamut:



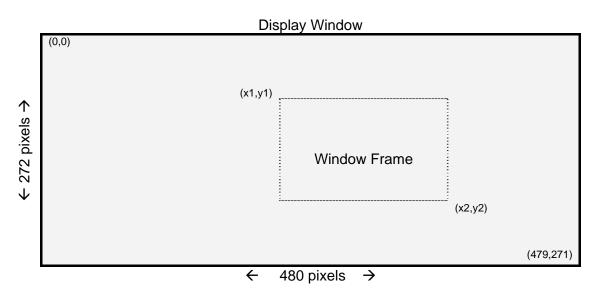
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8. Function Specifications

8.1 TFT Controller Functions

8.1.1 Display Memory Addressing

TFT module with 480x272 pixels, using SSD1963, address the display memory with a co-ordinate system as follow.



8.1.2 Command Packet

- Command Packet organizes with "Command Code" followed by "Parameter"
- Command Code and Parameters are 8bit only
- Number of Parameters is depends on Command type

me of the command followed with no parameter.

Se q.	D/C	/RD	/WR	Lo byte (D7:D0)
1	0	1	1	Command code
2	1	1	1	Parameter 1
3	1	1	1	Parameter 2
4	1	1	1	Parameter 3
:	:	:	:	:

8.1.3 Data Format

- Display Data is in 24bit format (R:G:B=8:8:8)
- 24bit data built one pixels
- Display Data could be continue write (depends on command and configuration)

D/C	/RD	/WR	D7	D6	D5	D4	D3	D2	D1	D0
1	1	1	R7	R6	R5	R4	R3	R2	R1	R0
1	1	1	G7	G6	G5	G4	G3	G2	G1	G0
1	1	1	B7	B6	B5	B 4	B 3	B2	B1	B0
1	1	1	R7	R6	R5	R4	R3	R2	R1	R0
1	1	1	G7	G6	G5	G4	G3	G2	G1	G0
1	1	1	B7	B6	B5	B 4	B 3	B2	B1	B0
:	•	:		•	:		-	:		:

8.1.4 Command Table

Code (hex)	Command	Description			
0x00	nop	No operation			
0x01	soft_reset	Software Reset			
0x0A	get_power_mode	Get the current power mode			
0x0B	get_address_mode	Get the frame buffer to the display panel read order			
0x0C	Reserved	Reserved			
0x0D	get_display_mode	The SSD1963 returns the Display Image Mode.			
0x0E	get_tear_effect_status	Get the Tear Effect status			
0x0F	Reserved	Reserved			
0x10	enter_sleep_mode	Turn off the panel. This command will pull low the GPIO0. If GPIO0 is configured as normal GPIO or LCD miscellaneous signal with command set_gpio_conf, this command will be ignored.			
0x11	exit_sleep_mode	Turn on the panel. This command will pull high the GPIO0. If GPIO0 is configured as normal GPIO or LCD miscellaneous signal with command set_gpio_conf, this command will be ignored.			
0x12	enter_partial_mode	Part of the display area is used for image display.			
0x13	enter_normal_mode	The whole display area is used for image display.			
0x20	exit_invert_mode	Displayed image colors are not inverted.			
0x21	enter_invert_mode	Displayed image colors are inverted.			
0x26	set_gamma_curve	Selects the gamma curve used by the display panel.			
0x28	set_display_off	Blanks the display panel			
0x29	set_display_on	Show the image on the display panel			
0x2A	set_column_address	Set the column address			
0x2B	set_page_address	Set the page address			
0x2C	write_memory_start	Transfer image information from the host processor interface to the SSD1963 starting at the location provided by set_column_address and set_page_address			
0x2E	read_memory_start	Transfer image data from the SSD1963 to the host processor interface starting at the location provided by set_column_address and set_page_address			
0x30	set_partial_area	Defines the partial display area on the display panel			
0x33	set_scroll_area	Defines the vertical scrolling and fixed area on display area			
0x34	set_tear_off	Synchronization information is not sent from the SSD1963 to the host processor			
0x35	set_tear_on	Synchronization information is sent from the SSD1963 to the host processor at the start of VFP			
0x36	set_address_mode	Set the read order from frame buffer to the display panel			
0x37	set_scroll_start	Defines the vertical scrolling starting point			
0x38	exit_idle_mode	Full color depth is used for the display panel			
0x39	enter_idle_mode	Reduce color depth is used on the display panel.			
0x3A	Reserved	Reserved			
0x3C	write_memory_continue	Transfer image information from the host processor interface to the SSD1963 from the last written location			
0x3E	read_memory_continue				
0x44	set_tear_scanline				
0x45	get_scanline	Get the current scan line			
0xA1	read_ddb	Read the DDB from the provided location			
0xA8	Reserved	Reserved			

8.1.5 Command Table(continue)

Code (hex)	Command	Description
0xB0	set_lcd_mode_	Set the LCD panel mode and resolution
0xB1	get_lcd_mode	Get the current LCD panel mode, pad strength and resolution
0xB4	set_hori_period	Set front porch
0xB5	get_hori_period	Get current front porch settings
0xB6	set_vert_period	Set the vertical blanking interval between last scan line and next LFRAME
		pulse
0xB7	get_vert_period	Set the vertical blanking interval between last scan line and next LFRAME
	9 <u>-</u>	pulse
0xB8	set_gpio_conf	Set the GPIO configuration. If the GPIO is not used for LCD, set the
0/12/0	eet_gp.e_eet	direction. Otherwise, they are toggled with LCD signals.
0xB9	get_gpio_conf	Get the current GPIO configuration
0xBA	set_gpio_value	Set GPIO value for GPIO configured as output
0xBB	get_gpio_status	Read current GPIO status. If the individual GPIO was configured as input,
UNDE	got_gpio_otatao	the value is the status of the corresponding pin. Otherwise, it is the
		programmed value.
0xBC	set_post_proc	Set the image post processor
0xBD	get_post_proc	Set the image post processor
0xBE	set_pwm_conf	Set the image post processor
0xBE 0xBF	get_pwm_conf	Set the image post processor
0xBF 0xC0	set_lcd_gen0	Set the rise, fall, period and toggling properties of LCD signal generator 0
0xC0		Get the current settings of LCD signal generator 0
0xC1 0xC2	get_lcd_gen0	
	set_lcd_gen1	Set the rise, fall, period and toggling properties of LCD signal generator 1
0xC3	get_lcd_gen1	Get the current settings of LCD signal generator 1
0xC4	set_lcd_gen2	Set the rise, fall, period and toggling properties of LCD signal generator 2
0xC5	get_lcd_gen2	Get the current settings of LCD signal generator 2
0xC6	set_lcd_gen3	Set the rise, fall, period and toggling properties of LCD signal generator 3
0xC7	get_lcd_gen3	Get the current settings of LCD signal generator 3
0xC8	set_gpio0_rop	Set the GPIO0 with respect to the LCD signal generators using ROP
		operation. No effect if the GPIO0 is configured as general GPIO.
0xC9	get_gpio0_rop	Get the GPIO0 properties with respect to the LCD signal generators.
0xCA	set_gpio1_rop	Set the GPIO1 with respect to the LCD signal generators using ROP
		operation. No effect if the GPIO1 is configured as general GPIO.
0xCB	get_gpio1_rop	Get the GPIO1 properties with respect to the LCD signal generators.
0xCC	set_gpio2_rop	Set the GPIO2 with respect to the LCD signal generators using ROP
	_	operation. No effect if the GPIO2 is configured as general GPIO.
Hex Code	Command	Description
0xCD	get_gpio2_rop	Get the GPIO2 properties with respect to the LCD signal generators.
0xCE	set_gpio3_rop	Set the GPIO3 with respect to the LCD signal generators using ROP
	-	operation. No effect if the GPIO3 is configured as general GPIO.
0xCF	get_gpio3_rop	Get the GPIO3 properties with respect to the LCD signal generators.
0xD0	set_dbc_conf	Set the dynamic back light configuration
0xD1	get_dbc_conf	Get the current dynamic back light configuration
0xD4	_set_dbc_th	Set the threshold for each level of power saving
0xD5	get_dbc_th	Get the threshold for each level of power saving
0xE0	set_pll	Start the PLL. Before the start, the system was operated with the crystal
		oscillator or clock input
0xE2	set_pll_mn	Set the PLL
0xE3	get_pll_mn	Get the PLL settings
0xE4	get_pll_status	Get the current PLL status
0xE5	set_deep_sleep	Set deep sleep mode
0xE6	set_lshift_freq	Set the LSHIFT (pixel clock) frequency
0xE7	get_lshift_freq	Get current LSHIFT (pixel clock) frequency setting
0xE8	Reserved	Reserved
0xE9	Reserved	Reserved
0xF0	set_pixel_data_interface	Set the pixel data format of the parallel host processor interface
0xF1	get_pixel_data_interface	Get the current pixel data format settings
0xFF	Reserved	Reserved
	Refer to SSD1963 datasheet for	

Note. Please Refer to SSD1963 datasheet for details.

URL: <u>www.topwaydisplay.com</u> www.topwaysz.com

8.1.6 Hardware Related Parameter

Booster and Power circuit

Internal TFT standBY and Backlight driver are controlled by SSD1963 GPIO0 and GPIO1 respectively. It is necessary to enable them for normal operation via command

Backlight Brightness PWM control

It is suggested to config the backlight brightness control signal as 3kHz PWM signal for best performance.

8.1.7 Startup Program (Example)

// wait for all power stable RST=1; delayms(10); RST=0; delayms(1); // reset pulse RST=1; delayms(10); // wait till internal reset routine finish SdCmd(0xe2); SdData(0x3B); SdData(0x02); SdData(0x04); delavms(10); // config PLL to 200MHz SdCmd(0xe0); SdData(0x01); delayms(10); // enable PLL SdCmd(0xe0); SdData(0x03); delayms(10); // switch to use PLL clock SdCmd(0x11); // exit_sleep_mode SdCmd(0x13); // enter_normal_mode (exit_partial_mode) SdCmd(0x20); // exit_invert_mode SdCmd(0x38); // exit_idle_mode (using full color) SdCmd(0xB8); // set_gpio_conf SdData(0x0f); // GPIO[0~3] controlled by host SdData(0x01); // GPIO0 as normal GPIO SdCmd(0xba); SdData(0x01); delayms(10); // GPIO[0~3]=0001, enable DC-CD booster SdCmd(0xba); SdData(0x03); delayms(10); // GPIO[0~3]=0011, enable backlight booster SdCmd(0xf0); SdData(0x00); // set_pixel_data_interface (MCU) 8bit SdCmd(0xb0); // set_lcd_mode SdData(0x24); // 24bit, disable FRC or dithering, DCLK=rising edge SdData(0x20); // HSYNC=active lo, VSYNC=active low, default TFT m // panel size 480-1 SdData(0x01); SdData(0xdf); SdData(0x01); SdData(0x0f); // panel size 272-1 SdCmd(0xb4); // set_hori_period SdData(0x02); SdData(0x0c); // total pulse per line, HT=525-1 SdData(0x00); SdData(0x2a); // horizontal front porch, HPS=41+2-1 SdData(0x07); // (default), not use SdData(0x00); SdData(0x00); // (default), not use SdData(0x00); // (default), not use SdCmd(0xb6); // set_vert_period SdData(0x01); SdData(0x1d); // total line per frame, VT=286-1 SdData(0x00); SdData(0x0b); // vertical front porch, VPS=10+2-1 SdData(0x09); // (default), not use SdData(0x00); SdData(0x00); // (default), not use SdCmd(0xe6); SdData(0x00); SdData(0xb8); SdData(0x50);// config PCLK=9.0MHz(PLL@200MHz) SdCmd(0x36);// set address mode SdData(0x00); // top to bottom, left to right, RGB, normal SdCmd(0xbe); // set_pwm_conf SdData(0x00); // PWM clock set to 3kHz (PLL@200MHz) SdData(150); // PWM width at about 60% (150/255) SdData(0x01); // C[3]=0, non_DBC control; C[0]=1, enable PWM SdData(0xf0); // DBC manual level at middle // DBC minimum lever at middle SdData(0x00); SdData(0x00); // disable the DBC response delay setting SdCmd(0x29); // display on SdCmd(0x2c); // write_memory_start SdData(0xff); SdData(0xff); SdData(0xff); // write a white pixel
// write a red pixel SdData(0xff); SdData(0x00); SdData(0x00); // continue write display data

Note. Above example program may need modification to fit correspondent application.

8.2 Touch Panel Controller Functions

8.2.1 ADS7843 Control Byte

Order of the control bits in the control byte

Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)
S	A2	A1	A0	MODE	SER/DFR	PD1	PD0

8.2.2 Descriptions of the Control Bits within the Control Byte.

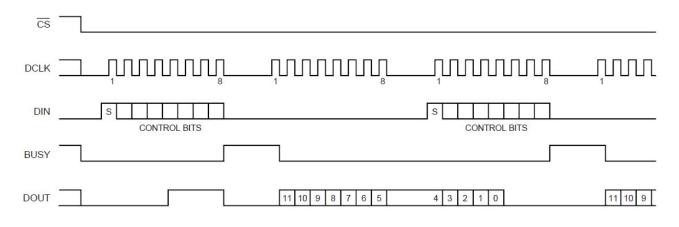
BIT	NAME	DESCRIPTION
7	S	Start Bit. Control byte starts with first HIGH bit on DIN. A new control byte can start every 16th clock cycle in 12-bit conversion mode or every 12th clock cycle in 8-bit conversion mode.
6-4	A2-A0	Channel Select Bits. Along with the SER/DFR bit, these bits control the setting of the multiplexer input, switches, and reference inputs.
3	MODE	12-Bit/8-Bit Conversion Select Bit. This bit controls the number of bits for the following conversion: 12bits (LOW) or 8 bits (HIGH).
2	SER/DFR	Single-Ended/Differential Reference Select Bit. Along with bits A2- A0, this bit controls the setting of the multiplexer input, switches, and reference inputs.
1-0	PD1-PD0	Power-Down Mode Select Bits.

8.2.3 Power-Down Selection.

PD1	PD0	PENIRQ	DESCRIPTION
0	0	Enable	Power-down between conversions. When each conversion is finished, the converter enters a low power mode. At the start of the next conversion,the device instantly powers up to full power.There is no need for additional delays to assure full operation and the very first conversion is valid. The Y– switch is on while in power-down.
0	1	Disable	Same as mode 00, except PENIRQ is disabled. The Y- switch is off while in power-down mode.
1	0	Disable	Reserved for future use.
1	1	Disable	No power-down between conversions, device is always powered.

8.2.4 Conversion Timing

16 Clocks per Conversion, 8-bit Bus Interface. No DCLK Delay Required with Dedicated Serial Port.



9. Precautions of using LCD Modules

Mounting

- Mounting must use holes arranged in four corners or four sides.
- The mounting structure so provide even force on to LCD module. Uneven force (ex. Twisted stress) should not applied to the module. And the case on which a module is mounted should have sufficient strength so that external force is not transmitted directly to the module.
- It is suggested to attach a transparent protective plate to the surface in order to protect the polarizer. It should have sufficient strength in order to the resist external force.
- The housing should adopt radiation structure to satisfy the temperature specification.
- Acetic acid type and chlorine type materials for the cover case are not desirable because the former generates corrosive gas of attacking the polarizer at high temperature and the latter causes circuit break by electro-chemical reaction.
- Do not touch, push or rub the exposed polarizers with glass, tweezers or anything harder than HB pencil lead. Never rub with dust clothes with chemical treatment. Do not touch the surface of polarizer for bare hand or greasy cloth. (Some cosmetics deteriorate the polarizer.)
- When the surface becomes dusty, please wipe gently with absorbent cotton or other soft materials like chamois soaks with petroleum benzine. Normal-hexane is recommended for cleaning the adhesives used to attach front / rear polarizers. Do not use acetone, toluene and alcohol because they cause chemical damage to the polarizer.

Wipe off saliva or water drops as soon as possible. Their long time contact with polarizer

Operating

- The spike noise causes the mis-operation of circuits. It should be within the ±200mV level (Over and under shoot voltage)
- Response time depends on the temperature.(In lower temperature, it becomes longer.)
- Brightness depends on the temperature. (In lower temperature, it becomes lower.) And in lower temperature, response time(required time that brightness is stable after turned on) becomes longer.
- Be careful for condensation at sudden temperature change. Condensation makes damage to polarizer or electrical contacted parts. And after fading condensation, smear or spot will occur.
- When fixed patterns are displayed for a long time, remnant image is likely to occur.
- Module has high frequency circuits. Sufficient suppression to the electromagnetic interference shall be done by system manufacturers. Grounding and shielding methods may be important to minimized the interference

Electrostatic Discharge Control

Since a module is composed of electronic circuits, it is not strong to electrostatic discharge. Make certain that treatment persons are connected to ground through wrist band etc. And don't touch interface pin directly.

Strong Light Exposure

Strong light exposure causes degradation of polarizer and color filter.

Storage

When storing modules as spares for a long time, the following precautions are necessary.

- Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 35°C at normal humidity.
- The polarizer surface should not come in contact with any other object. It is recommended that they be stored in the container in which they were shipped.

Protection Film

- When the protection film is peeled off, static electricity is generated between the film and polarizer. This should be peeled off slowly and carefully by people who are electrically grounded and with well ion-blown equipment or in such a condition, etc.
- The protection film is attached to the polarizer with a small amount of glue. If some stress is applied to rub the protection film against the polarizer during the time you peel off the film, the glue is apt tore main on the polarizer. Please carefully peel off the protection film without rubbing it against the polarizer.
- When the module with protection film attached is stored for a long time, sometimes there remains a very small amount of glue still on the polarizer after the protection film is peeled off.
- You can remove the glue easily. When the glue remains on the polarizer surface or its vestige is recognized, please wipe them off with absorbent cotton waste or other soft material like chamois soaked with normal-hexane.

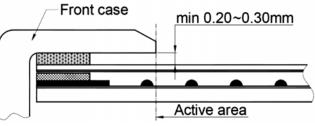
Transportation

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

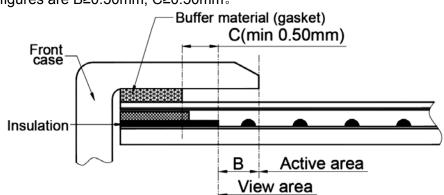
附录: Touch panel Design Precautions

 It should prevent front case touching the touch panel Active Area (A.A.) to prevent abnormal touch.

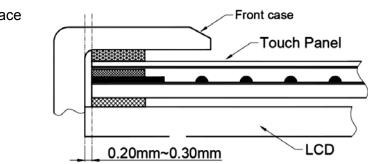
It should left gab (e.g. 0.2~0.3mm) in between.



 Outer case design should take care about the area outside the A.A. Those areas contain circuit wires which is having different thickness. Touching those areas could deform the ITO film. As a result case the ITO cold be damaged and shorten its lifetime. It is suggested to protect those areas with gasket (between the front case and the touch panel). The suggested figures are B≥0.50mm; C≥0.50mm_☉

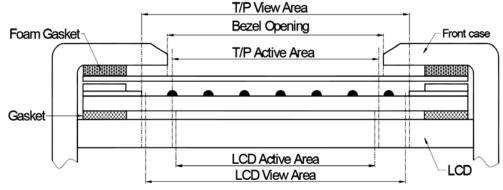


3. The front case side wall should keep space (e.g. 0.2 ~ 0.3mm) from the touch panel.



4. In general design,

touch panel V.A. should be bigger than the LCD V.A. and touch panel A.A. should be bigger than the LCD A.A.



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